	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company unique ID Unique ID Authority Response Date* 2024-05-10 Contact Name Title - Contact Product Enviro Compliance NA Product-Env-Stewards NA Product-Env-Stewards NA Product-Env-Stewards NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Pr	752-21.1											als and Mfg	Informati	on	
Semilar Contact Name Title - Contact Phone - Contact* Phone - Contact* Product Envisor Compliance NA Product Envisor Stewards Product Envisor Compliance Product Envisor Envisor Compliance Product Envisor En	upplier Informa	1 1 3													
Title - Contact Name Product Envi-Stewards	Company name* Company unique ID					Ţ	Unique ID Authority				Response Date*				
Product Envisor Compliance Unthorized Representative* Title - Representative Product Enviror Compliance Product Envisor Compliance NA Product Envisor Stewards @onsemi.com NA Na Naufacturing Site Weight* UOM UI Naufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Nax Time at Peak Temperature Number of Reflow Cycles Natte Tin (Sn) - annealed OU Alloy 3 260 © 30 seconds 3	nsemi									2024-05-10					
Authorized Representative* Title - Representative Product Envi-Stewards Product-Env-Stewards Onsemi.com Manufacturing Site Weight* UOM Un FAN604HMX QR Flyback CCR pin to 20V 2024-05-10 TAD 77.8214 mg Ea Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 3 260 C 30 seconds 3	ontact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
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		(Sn) - annealed		U Alloy	3			200		IC	30	seconds	3 3		
1 TENTION: MISE 3 Rated tiem requires bake and Dry Pack (after electrical test)		2 D_4-1 '4 D	.l.,	Dl- (- %											
or more information regarding material composition please refer to page 3		*			,										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and certed to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.43	mg	Supplier	Silicon (Si)	7440-21-3		1.43	mg
Die Attach	0.0631	mg		Epoxy resin	proprietary data		0.0063	mg
			Supplier	Silver (Ag)	7440-22-4		0.0505	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0063	mg
Lead Frame	25.2775	mg	Supplier	Silver (Ag)	7440-22-4		0.0202	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0506	mg
			Supplier	Iron (Fe)	7439-89-6		0.632	mg
			Supplier	Copper (Cu)	7440-50-8		24.5494	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0253	mg
Mold Compound-Black	48.6018	mg		Epoxy resin	proprietary data		3.4021	mg
			Supplier	Phenolic Resin	Proprietary Data		1.4581	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.8602	mg
			Supplier	Carbon Black (C)	1333-86-4		0.243	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6384	mg
Plating	2.37	mg	Supplier	Tin (Sn)	7440-31-5		2.37	mg
Wire Bond - Au	0.079	mg	Supplier	Gold (Au)	7440-57-5		0.079	mg